

East 10/706 624

L Number	Hits	Search Text	DB	Time stamp
1	20986	plasma and etching and heating and (wafer or semiconductor)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 12:56
2	1663	wafer and boat and (batch or plurality adj4 wafers)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 12:57
4	16986	microwave with heating	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 12:58
5	441	(plasma and etching and heating and (wafer or semiconductor)) and (microwave with heating)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:01
6	0	oscillat\$ and polar adj molocules	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:02
7	0	polar adj molocules	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:03
8	1621	dipoles and oscill\$	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:03
9	463	microwave\$ and (dipoles and oscill\$)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:04
11	0	(wafer and boat and (batch or plurality adj4 wafers)) and (microwave\$ and (dipoles and oscill\$))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:04
10	8	(plasma and etching and heating and (wafer or semiconductor)) and (microwave\$ and (dipoles and oscill\$))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:19
12	2865	DRYING ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:49
14	3	(DRYING ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) adj5 microwave	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:30
13	6	(DRYING ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) with microwave	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:30
15	4	(DRYING ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) adj7 microwave	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:46
16	9756	cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:48
17	74	(removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:48
18	175	(removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:48

19	9843	(cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:48
20	47	((cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP))) with microwave	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:49
21	14985	heating ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:49
22	108	heating ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP) with microwave	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:50
23	152	((((cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP))) with microwave) or (heating ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP) with microwave)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:50
24	30949	after adj2 etching	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:50
25	0	(after adj2 etching) with (((cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP))) with microwave) or (heating ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP) with microwave)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:51
26	3651	(plasma and etching and heating and (wafer or semiconductor)) and (after adj2 etching)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:51
27	58	(plasma and etching and heating and (wafer or semiconductor)) and (((cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP))) with microwave) or (heating ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP) with microwave)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 14:11
28	7	(heating with microwave) with plasma adj chamber	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:53
29	17	(heating with microwave) with plasma adj (vessel or reactor or chamber)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:54
30	0	(heating with microwave) adj4 (plasma adj (vessel or reactor or chamber))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:54
31	0	(heating with microwave) adj7 (plasma adj (vessel or reactor or chamber))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:54
32	17	((heating with microwave) with plasma adj chamber) or ((heating with microwave) with plasma adj (vessel or reactor or chamber))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 13:55

33	152	((plasma and etching and heating and (wafer or semiconductor)) and (((((cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP))) with microwave) or (heating ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP) with microwave))) or (((((cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP))) with microwave) or (heating ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP) with microwave)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 14:12
34	1	(after adj2 etching) with (heating adj4 microwave)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 14:14
35	71124	purging or evacuating	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 14:14
37	71142	(purging or evacuating) or (((((cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP))) with microwave) or (heating ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP) with microwave)) with (heating adj4 microwave))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 14:15
38	0	(purging or evacuating) and (((((cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP))) with microwave) or (heating ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP) with microwave)) with (heating adj4 microwave))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 14:15
36	18	(((cleaning ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj residue) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP)) or ((removing adj contaminants) ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP))) with microwave) or (heating ADJ5 (WAFER OR SEMICONDUCTOR OR CHIP) with microwave)) with (heating adj4 microwave)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2004/08/17 14:15